

Product Features:

Low Cost SMD Package
Ultra Miniature Package
Compatible with Leadfree Processing

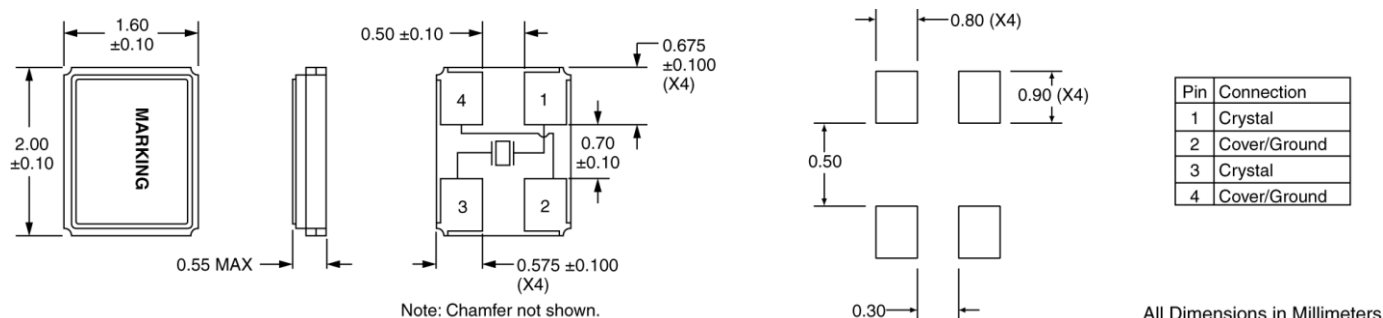
Applications:

Fibre Channel
Server & Storage
Sonet / SDH
802.11 / WiFi
T1/E1, T3/E3

Electrical Specifications

Frequency	16MHz to 72MHz
Equivalent Series Resistance 16MHz – 23.999999MHz 24MHz – 25.999999MHz 26MHz – 72MHz	150 Ohms Maximum 80 Ohms Maximum 60 Ohms Maximum
Shunt Capacitance (C0)	3pF Maximum
Frequency Tolerance (at 25°C)	±50ppm, ±30ppm, ±25ppm, ±20ppm, ±15ppm, or ±10ppm
Frequency Stability (over Temperature)	±50ppm, ±30ppm, ±25ppm, ±20ppm, ±15ppm, or ±10ppm
Mode of Operation	Fundamental
Crystal Cut	AT Cut
Load Capacitance	8pF to 32pF or Specify
Drive Level	100µW Maximum
Aging	±5ppm/Year Maximum
Operating Temperature Range	See Part Number Guide
Storage Temperature Range	-40°C to +85°C

Mechanical and Solder Pad Dimensions

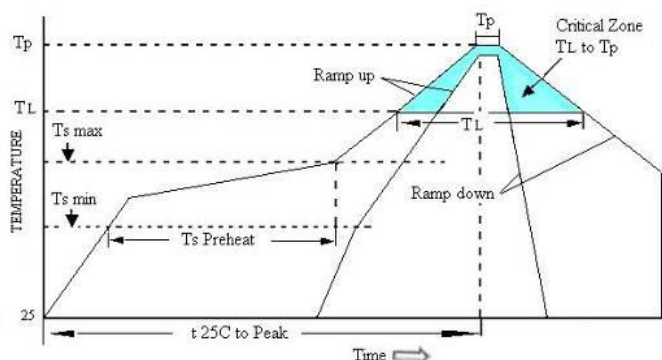


Part Number Guide

Sample Part Number: ILCX19 – FB1F18 - 20.000 MHz						
Package	Frequency Tolerance	Frequency Stability	Operating Temperature Range	Mode of Operations	Load Capacitance	Frequency
ILCX19 -	B = ±50ppm	B = ±50ppm	0 = 0°C to +50°C	F = Fundamental	8pF to 32pF or Specify	20.000 MHz
	F = ±30ppm	F = ±30ppm	1 = 0°C to +70°C			
	G = ±25ppm	G = ±25ppm	2 = -10°C to +60°C			
	H = ±20ppm	H = ±20ppm	3 = -20°C to +70°C			
	I = ±15ppm	I = ±15ppm*, **	5 = -40°C to +85°C			
	J = ±10ppm*	J = ±10ppm*, **	9 = -10°C to +50°C			

* Not available at all frequencies. ** Not available for all temperature ranges.

Pb Free Solder Reflow Profile:



Units are backward compatible with +240°C reflow processes

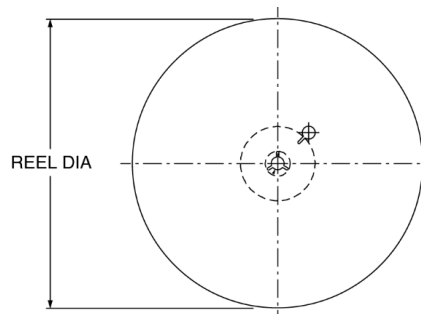
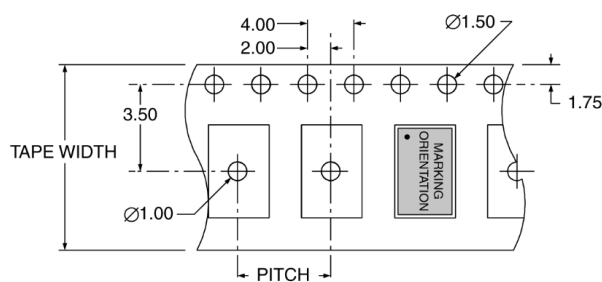
Ts max to T _L (Ramp-up Rate)	3°C / second max
Preheat	
Temperature min (Ts min)	150°C
Temperature typ (Ts typ)	175°C
Temperature max (Ts max)	200°C
Time (Ts)	60 to 180 seconds
Ramp-up Rate (T _L to Tp)	3°C / second max
Time Maintained Above Temperature (T _L)	217°C
Time (T _L)	60 to 150 seconds
Peak Temperature (Tp)	260°C max for 10 seconds
Time within 5°C to Peak Temperature (Tp)	20 to 40 seconds
Ramp-down Rate	6°C / second max
Time 25°C to Peak Temperature	8 minutes max

Package Information:

MSL = 1 (package does not contain plastic, storage life is unlimited under normal room conditions)

Termination = e4 (Au over Ni over W base metallization)

Tape and Reel Information:



PITCH	4.00
TAPE WIDTH	8.00
REEL DIA	180
QTY PER REEL	3,000

Environmental Specifications:

Mechanical Shock	MIL-STD-202, Method 213
Vibration	MIL-STD-202, Method 204
Resistance to Soldering Heat	MIL-STD-202, Method 210
Solderability	J-STD-002
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2

Marking:

Line 1: I, Date Code (YWW)